

CAVITY CHIP PACKAGE

ABSTRACT

A package for an IC includes a carrier with a cavity formed on one of the major surfaces. Bumps of a semiconductor die are mated to contact pads located on the bottom of the cavity. The die is attached to the major surface of the carrier. The major surface creates a support which securely holds the chip in place with adhesive for assembly.

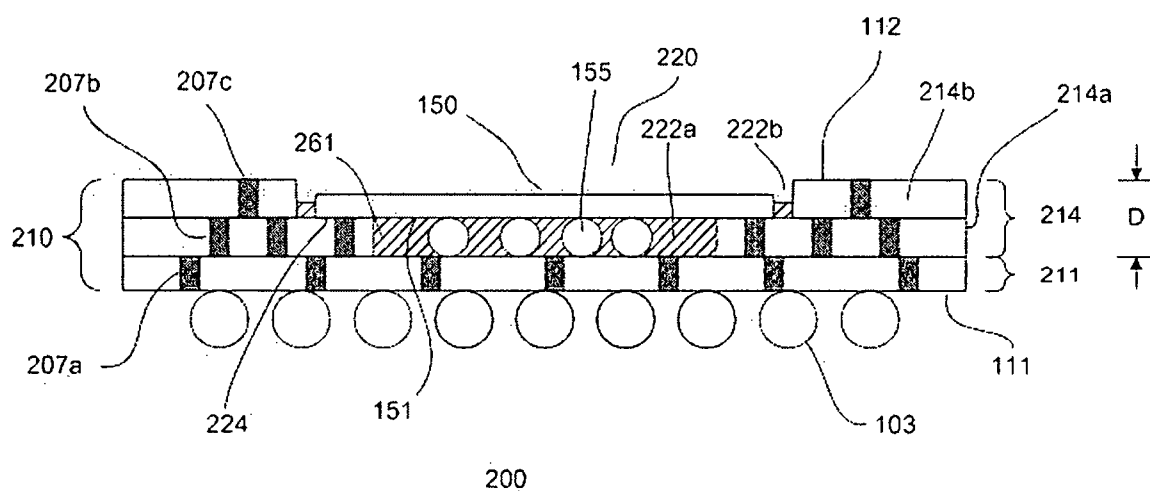


Fig. 2a



162162



G00002